

ABSTRACT

Disclosed is a manufacturing method for a support piece used in a manufacturing process of a semiconductor device having a dolmen structure including a substrate, a first chip disposed on the substrate, a plurality of support pieces disposed around the first chip, on the substrate, and a second chip disposed to be supported by the plurality of support pieces and to cover the first chip, the method including: (A) preparing a laminate film including a base material film, an adhesive layer, and a support piece formation film, in this order; (B) forming support pieces on a surface of the adhesive layer by singulating the support piece formation film; and (C) picking up the support piece from the adhesive layer, in which a shear viscosity of the support piece formation film at 120°C is 4000 Pa·s or more.

Fig. 1